## 捷多邦,专业PCB打样工**54AQ不16827** 20-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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- Members of the Texas Instruments
  Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines Directly
- Flow-Through Architecture Optimizes
  PCB Layout
- Distributed V<sub>CC</sub> and GND Pin Configuration
  Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

#### description

The 'ACT16827 are noninverting 20-bit buffers composed of two 10-bit sections with separate output-enable signals. For either 10-bit buffer section, the two output-enable (10E1 and 10E2 or 20E1 and 20E2) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer section are in the high-impedance state.

The 74ACT16827 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

54ACT16827 . . . WD PACKAGE 74ACT16827 . . . DL PACKAGE (TOP VIEW)

- 1			
10E1	1	56	10E2
1Y1 [	2	55	1A1
1Y2 [	3	54	1A2
GND [	4	53	GND
1Y3 [	5	52	1A3
1Y4 [	6	51	A14
v <sub>cc</sub> [	7	50	] v <sub>cc</sub>
1Y5 [	8	49	] 1A5
1Y6 🛚	9	48	1A6
1Y7 🛚	10	47	] 1A7
GND [	11	46	GND
1Y8 [	12	45	] 1A8
1Y9 [	13	44	1A9
1Y10	14	43	1A10
2Y1 [	15	42	2A1
2Y2 [	16	41	2A2
2Y3 [	17	40	2A3
GND [	18	39	GND
2Y4 [	19	38	2A4
2Y5 [	20	37	2A5
2Y6 [	21	36	2A6
v <sub>cc</sub> [	22	35	Vcc
2Y7	23	34	2A7
2Y8 [	24	33	2A8
GND [	25	32	GND
2Y9 [	26	31	2A9
2Y10	27	30	2A10
20E1	28	29	20E2

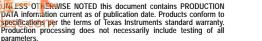
The 54ACT16827 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16827 is characterized for operation from –40°C to 85°C.

## FUNCTION TABLE (each 8-bit section)

(outil o bit ootiloii)							
ZM	INPUTS		OUTPUT				
OE1	OE2	Α	Y				
0.5	L	L	L				
L	L	Н	н				
Н	X	Χ	Z				
Х	Н	Χ	Z				

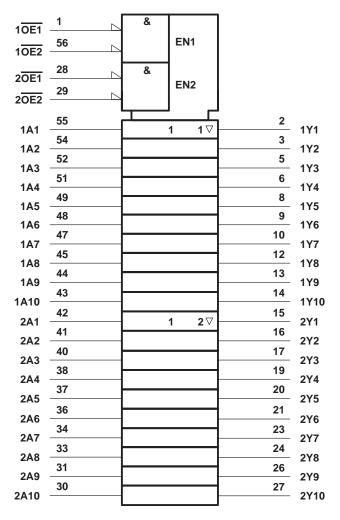
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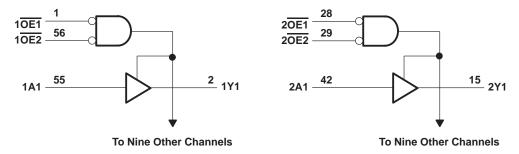


#### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)





#### absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> –0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)
Output voltage range, $V_O$ (see Note 1)
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )
Continuous current through V <sub>CC</sub> or GND ±500 mA
Maximum package power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2): DL package 1.4 W
Storage temperature range, T <sub>stg</sub> –65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 3)

		54ACT16827		54ACT16827			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		7	2			V
VIL	Low-level input voltage			0.8			0.8	V
VI	Input voltage	0	200	<sup>/</sup> Vcc	0		VCC	V
Vo	Output voltage	0	7.	Vcc	0		Vcc	V
IOH	High-level output current		2	-24			-24	mA
lOL	Low-level output current		0	24			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	0		10	ns/V
TA	Operating free-air temperature	-55	_	125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS	Vaa	T,	Δ = 25°C	;	54ACT16827		74ACT16827		UNIT
PARAMETER		VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Jour 50 HA	4.5 V	4.4			4.4		4.4		
	ΙΟΗ = -50 μΑ	5.5 V	5.4			5.4		5.4		1 1
Voн	I <sub>OH</sub> = -24 mA	4.5 V	3.94			3.8		3.8		V
	10H = -24 IIIA	5.5 V	4.94			4.8		4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		3.85		
	ΙΟL = 50 μΑ	4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
VOL	I <sub>OL</sub> = 24 mA	4.5 V			0.36	4	0.44		0.44	V
		5.5 V			0.36	Č,	0.44		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V				20	1.65		1.65	
lį	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1	Dy.	±1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5	4	±5		±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
ΔI <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			0.9		1		1	mA
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4.5						pF
Co	$V_O = V_{CC}$ or GND	5 V		16						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	OM TO T <sub>A</sub> = 25°C		;	54ACT16827		74ACT16827		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	А		3.6	7.4	9.8	3.6	11	3.6	11	ns
<sup>t</sup> PHL	A	Ť	2.8	7.4	9.8	2.8	10.8	2.8	10.8	115
<sup>t</sup> PZH	<del></del>	<b>&gt;</b>	3	7.9	10.4	3	11.7	3	11.7	no
<sup>t</sup> PZL	ŌĒ	, , ,	4	9.6	12.4	40	14	4	14	ns
<sup>t</sup> PHZ	<del></del>		5.8	9.1	11.3	5.8	12.4	5.8	12.4	no
tPLZ	OE	ī	5.3	8.5	10.5	5.3	11.5	5.3	11.5	ns

## operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

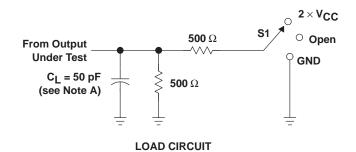
	PARAMETER		TEST CO	NDITIONS	TYP	UNIT
<u> </u>	Dower dissination capacitance	Outputs enabled	C 50 pF	f = 1 MHz	41	n.E
Cpd	Power dissipation capacitance	Outputs disabled	$C_L = 50 \text{ pF},$	I = I IVIDZ	10	рF



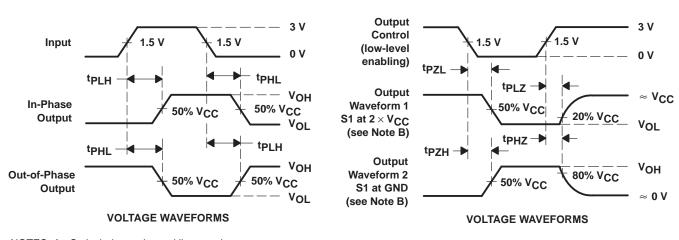
<sup>‡</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

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#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	2×V <sub>CC</sub>
tPHZ/tPZH	GND



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 3 \ ns$ ,  $t_f = 3 \ ns$ .
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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